

## DESCRIPTION

The HX2300A uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and high density cell Design for ultra low on-resistance. This device is suitable for use as a load switch or in PWM applications.

## GENERAL FEATURES

- ◆  $V_{DS} = 20V$ ,  $I_D = 2.5A$
- $R_{DS(ON)}(\text{Typ.}) = 61\text{m}\Omega$       @  $V_{GS} = 2.5V$
- $R_{DS(ON)}(\text{Typ.}) = 46\text{m}\Omega$       @  $V_{GS} = 4.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

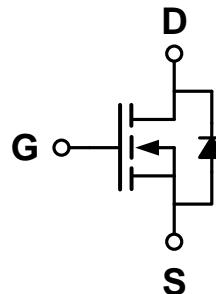
## APPLICATION

- ◆ PWM applications
- ◆ Load switch

## PACKAGE

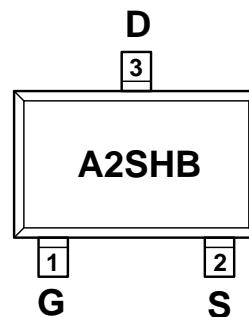
- ◆ SOT-23

## SCHEMATIC DIAGRAM



## PIN ASSIGNMENT

SOT-23  
(TOP VIEW)



## ORDERING INFORMATION

Part Number	Storage Temperature	Package	Marking	Devices Per Reel
<b>HX2300A</b>	-55°C to +150°C	SOT-23	A2SHB	3000

## ABSOLUTE MAXIMUM RATINGS

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	20	V
Gate-source voltage	$V_{GS}$	$\pm 12$	V
Continuous drain current ( $T_J = 150^\circ\text{C}$ ) <sup>a</sup>	$I_A=25^\circ\text{C}$	2.5	A
	$T_A=70^\circ\text{C}$	2.0	
Pulsed drain current <sup>b</sup>	$I_{DM}$	10	
Continuous source current (diode conduction) <sup>a</sup>	$I_S$	0.6	
Power dissipation <sup>a</sup>	$T_A=25^\circ\text{C}$	0.71	W
	$T_A=70^\circ\text{C}$	0.46	
Operating junction and storage temperature range	$T_J, T_{stg}$	-55—150	°C

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Maximum junction-to-ambient <sup>a</sup>	≤ 5 s	$R_{\theta JA}$	120	145
	Steady-State		140	175
Maximum junction-to-foot	Steady-State	$R_{\theta JC}$	62	78

### Notes

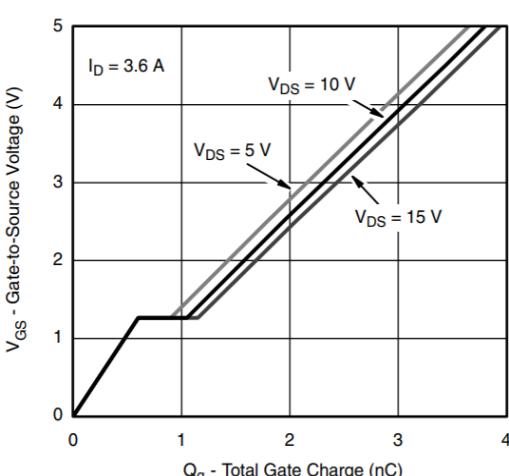
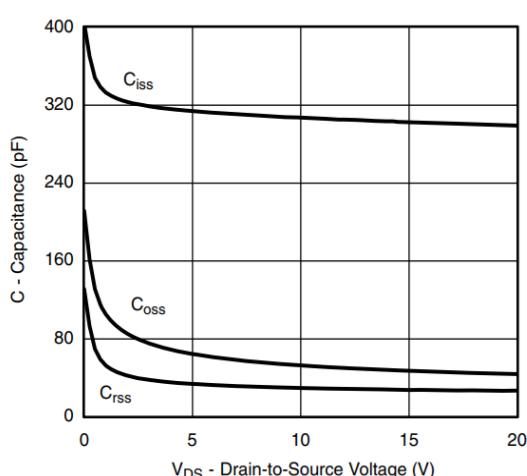
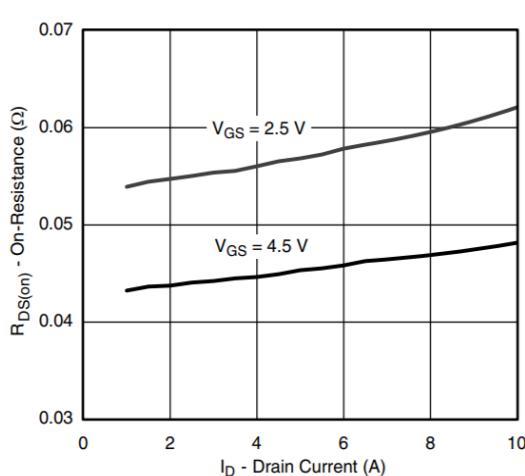
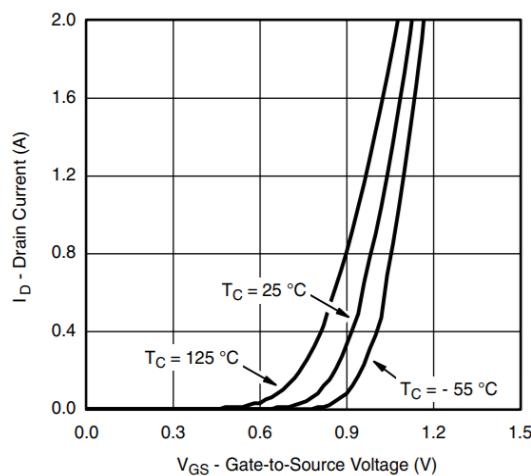
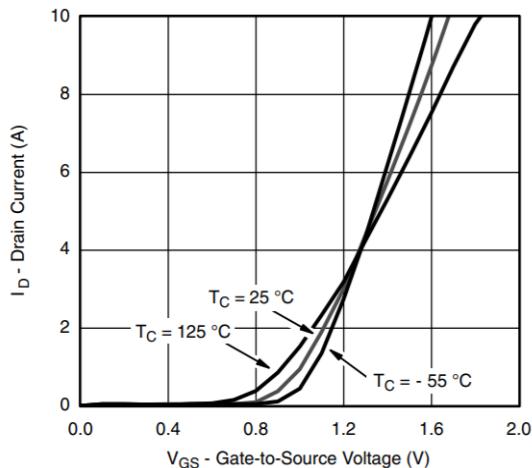
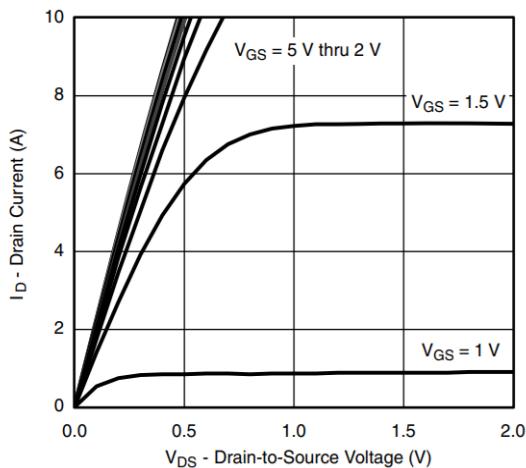
- a. Surface mounted on 1" x 1" FR4 board
- b. Pulse width limited by maximum junction temperature

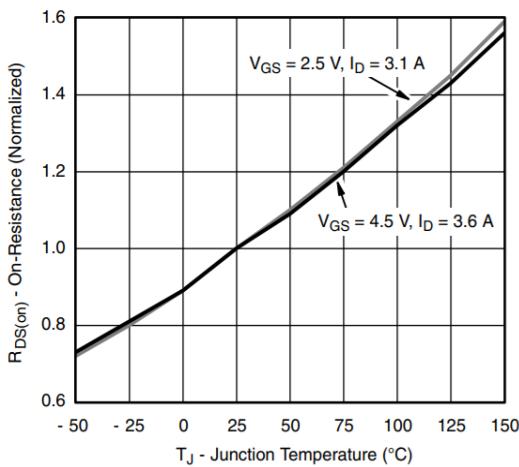
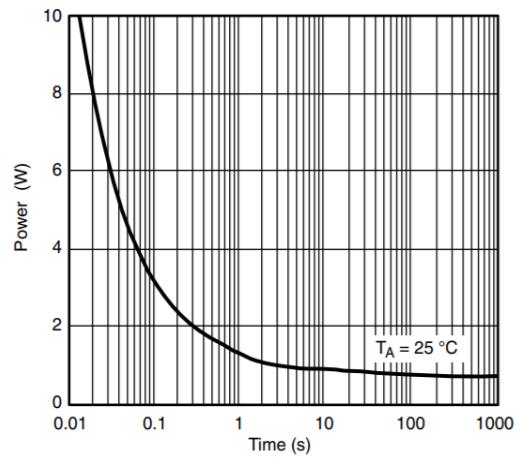
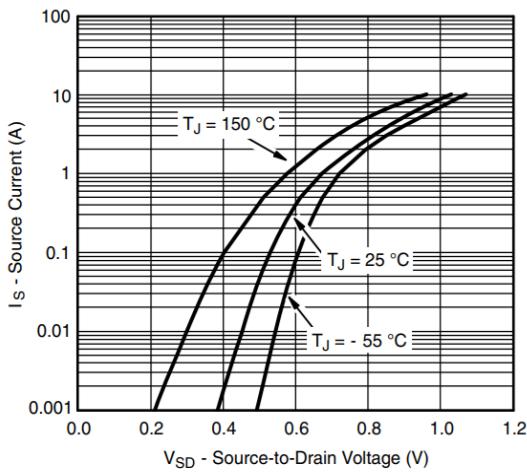
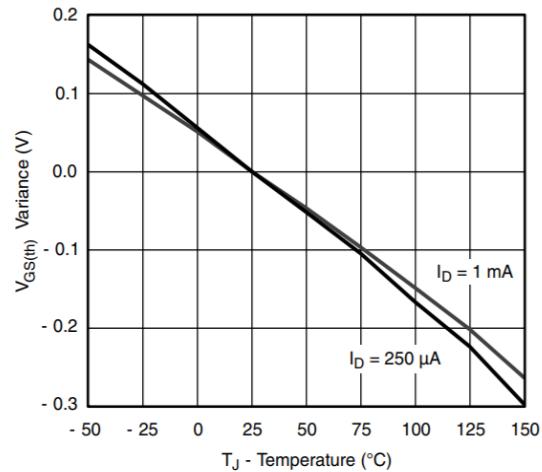
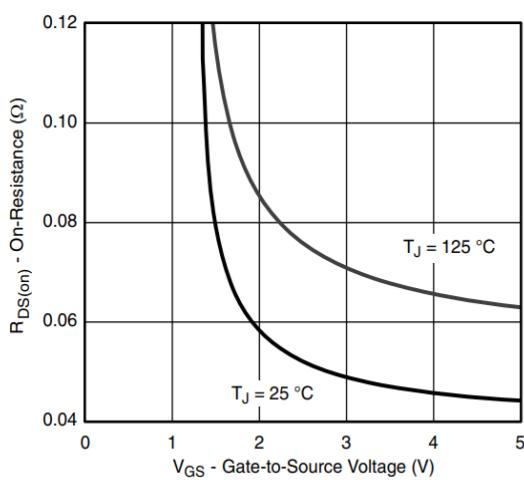
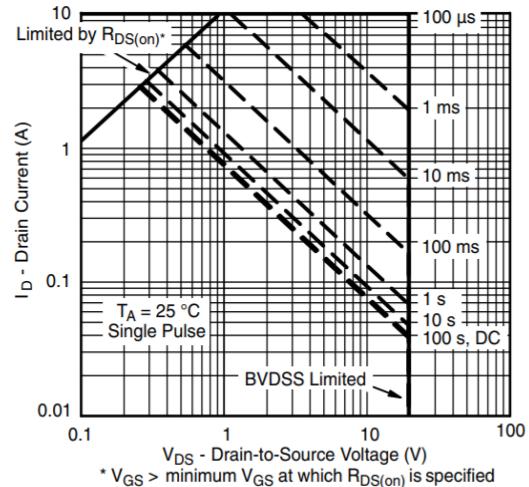
## Electrical Characteristics ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=20V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-body leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 12V$	-	-	$\pm 100$	nA
<b>ON Characteristics</b>						
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.65	1.0	V
Drain-source on-state resistance <sup>a</sup>	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=2.5A$	-	46	60	$m\Omega$
		$V_{GS}=2.5V, I_D=1A$	-	61	85	
Forward transconductance <sup>a</sup>	$g_{fs}$	$V_{DS}=5V, I_D=2A$	-	5	-	S
<b>Dynamic Characteristics <sup>b</sup></b>						
Input capacitance	$C_{iss}$	$V_{DS}=10V, V_{GS}=0V$ $f=1.0MHz$	-	180	-	pF
Output capacitance	$C_{oss}$		-	38	-	
Reverse transfer capacitance	$C_{rss}$		-	20	-	
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{D(ON)}$	$V_{DD}=10V$ $R_L=3\text{ ohm}$ $V_{GEN}=4.5V$ $R_{GEN}=6ohm$	-	8	-	ns
Rise time	$tr$		-	7	-	
Turn-off delay time	$t_{D(OFF)}$		-	30	-	
Fall time	$tf$		-	7	-	
Total gate charge	$Q_g$	$V_{DS}=10V$ $I_D=2.5A$ $V_{GS}=4.5V$	-	3.5	-	nC
Gate-source charge	$Q_{gs}$		-	0.6	-	
Gate-drain charge	$Q_{gd}$		-	0.45	-	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode forward voltage	$V_{SD}$	$V_{GS}=0V, I_s=2.5A$	-	0.76	1.16	V

### Notes

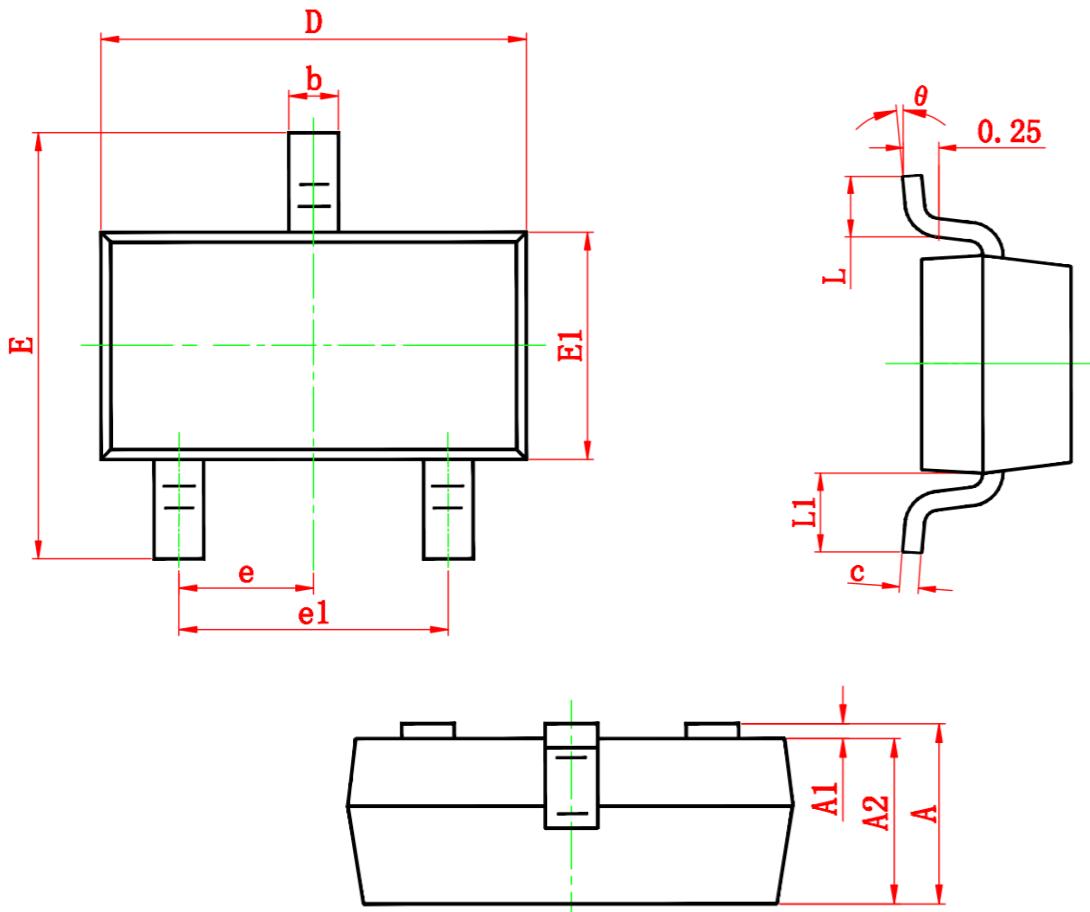
- a. Pulse test: Pulse width ≤ 300 μs, duty cycle ≤ 2 %
- b. Guaranteed by design, not subject to production testing

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**On-Resistance vs. Junction Temperature**

**Single Pulse Power**

**Source-Drain Diode Forward Voltage**

**Threshold Voltage**

**On-Resistance vs. Gate-to-Source Voltage**

**Safe Operating Area, Junction-to-Ambient**

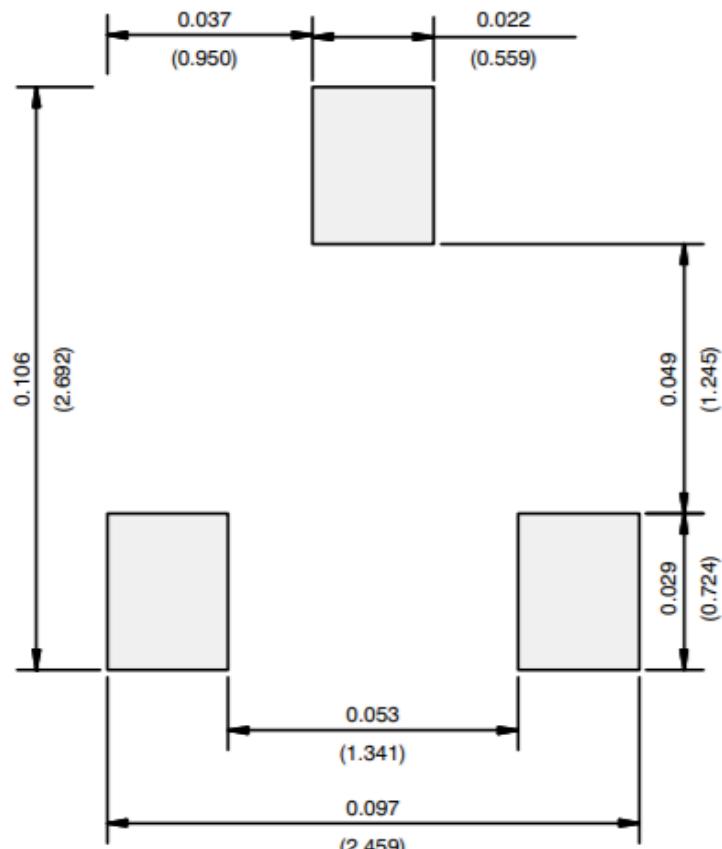
## PACKAGE INFORMATION

- SOT-23



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	2.250	2.550	0.089	0.100
E1	1.200	1.400	0.047	0.055
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.300	0.500	0.012	0.020
L1	0.550 REF.		0.022 REF.	
θ	0°	8°	0°	8°

## RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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